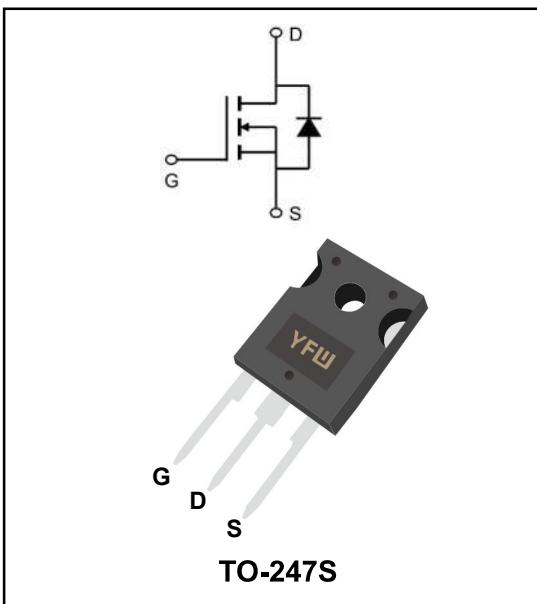


150V N-Channel Enhancement Mode Power MOSFET
MAIN CHARACTERISTICS

I_D	200A
V_{DSS}	150V
$R_{DS(on)-typ}(@V_{GS}=10V)$	<7.5mΩ(Typ:6.2 mΩ)


FEATURES

- YFW-SGT technology
- DC/DC Converter
- LED Backlighting
- Power Management Switches

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	150	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous drain current, $V_{GS} @ 10V$ @ $T_c=25^\circ\text{C}$	I_D	200	A
Continuous drain current, $V_{GS} @ 10V$ @ $T_c=100^\circ\text{C}$	I_D	140	A
Pulsed Drain Current (Note1)	I_{DM}	550	A
Single Pulse Avalanche Energy	E_{AS}	506	mJ
Avalanche Current	I_{AS}	53.4	A
Total Power Dissipation ⁴	P_D	278	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Temperature Range	T_J	-55 to +150	°C
Thermal Resistance, Junction to Ambient	$R_{θJA}$	0.45	°C/W
Thermal Resistance, Junction to Case	$R_{θJC}$	62	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	BV _{DSS}	150	-	-	V
Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Zero Gate Voltage Drain Current T _J =25°C	V _{DS} =100V, V _{GS} =0V	I _{DSS}	-	-	1	μA
Zero Gate Voltage Drain Current T _J =100°C		I _{DSS}	-	-	100	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	V _{GS(th)}	2.0	3.0	4.0	V
Drain-Source On-State Resistance ²	V _{GS} = 10 V, I _D = 40 A	R _{DSS(ON)}	-	6.2	7.5	mΩ
Input Capacitance	V _{GS} =0V V _{DS} =50V f=1MHz	C _{iss}	-	5240	-	pF
Output Capacitance		C _{oss}	-	412	-	
Reverse Transfer Capacitance		C _{rss}	-	10	-	
Gate Resistance	V _{GS} = 0V, V _{DS} = 0V, f =1MHz V _{GS} = 10V, V _{DS} = 50V, I _D =20A	R _G	-	1.7	-	Ω
Total Gate Charge		Q _g	-	18	-	nC
Gate-Source Charge		Q _{gs}	-	10	-	
Gate-Drain Charge		Q _{gd}	-	72	-	
Turn-on delay time	V _{GS} =10V V _{DS} =50V R _G =3Ω I _D = 20A	t _{d(on)}	-	22	-	ns
Rise Time		T _r	-	115	-	
Turn-Off Delay Time		t _{d(OFF)}	-	44	-	
Fall Time		t _f	-	105	-	
Diode Forward Voltage ²	I _F = 20A, V _{GS} = 0V	V _{SD}	-	-	1.2	V
Diode forward current ¹⁻⁵	V _G =V _D =0V, Force Current	I _s	-	-	200	A
Reverse Recovery Time	I _F = 20A dI _F / dt = 100 A/μs	t _{rr}	-	45	-	ns
Reverse Recovery Charge		Q _{rr}	-	12	-	nC

Notes:

- 1、The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V_{DD}=50V, V_{GS}=10V, L=0.5mH, I_{AS}=45A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

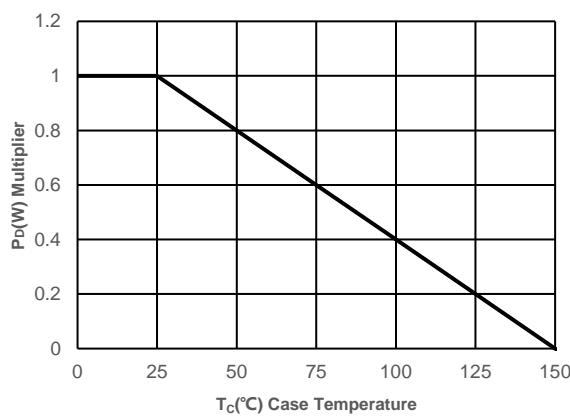


Figure 1. Power dissipation

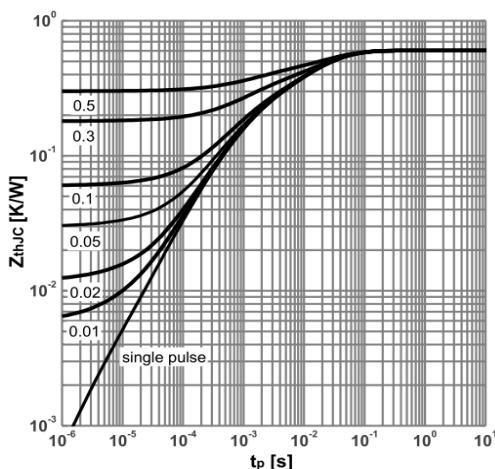


Figure 2. Max. transient thermal impedance

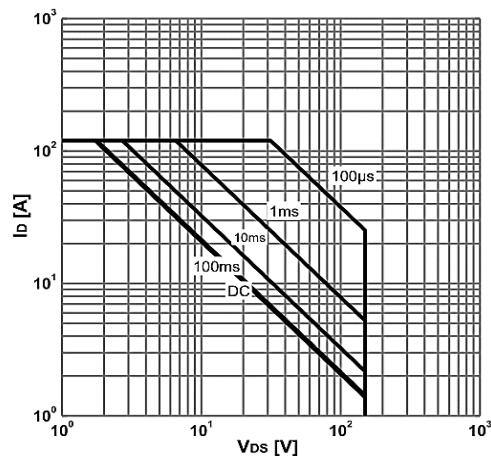


Figure 3. Safe operating area

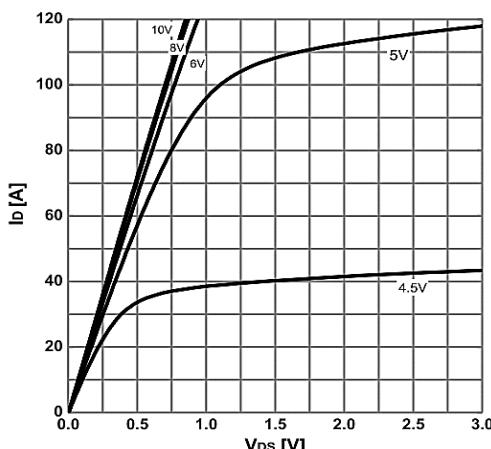


Figure 4. Typ. output characteristics

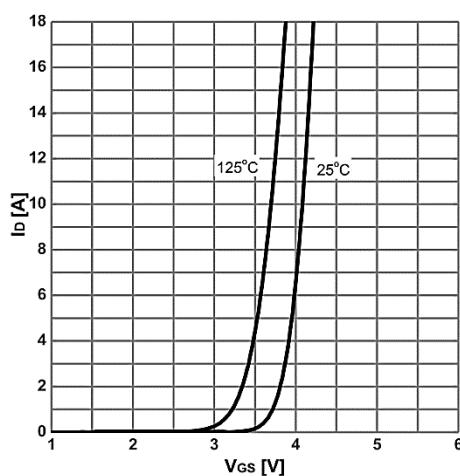


Figure 5. Typ. transfer characteristics

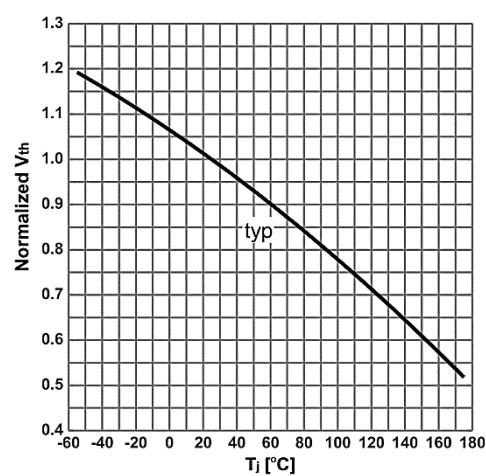


Figure 6. Gate threshold voltage vs. Junction Temperature

Typical Characteristics

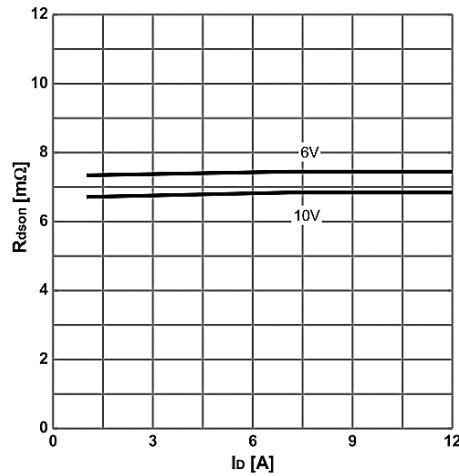


Figure 7. On-state resistance vs. Drain current

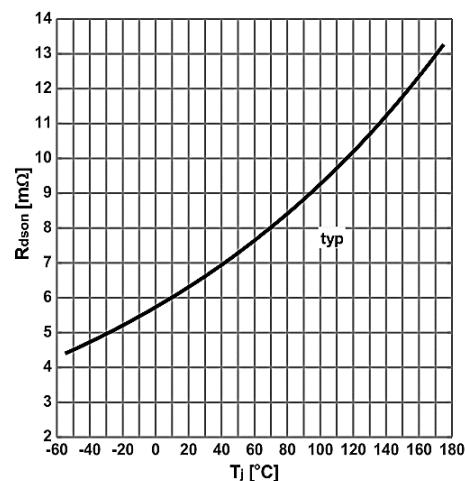


Figure 8. On-state resistance vs. Junction temperature

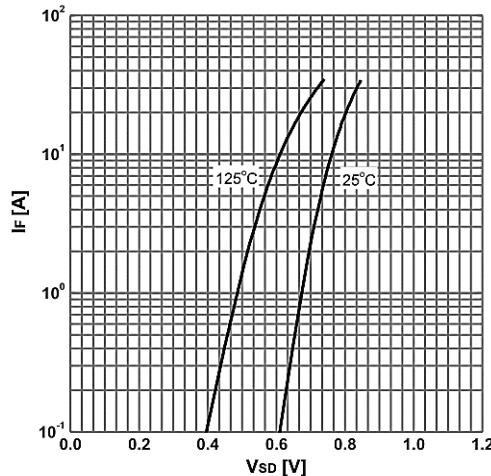


Figure 9. Forward characteristics of reverse diode

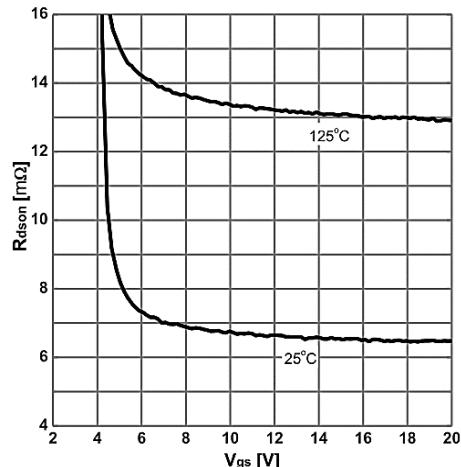


Figure10. On-state resistance vs. Vgs characteristics

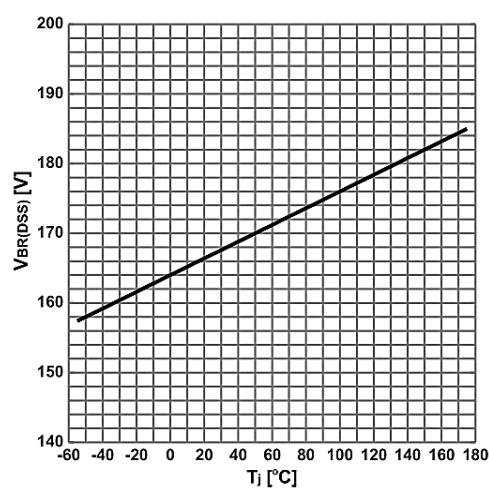


Figure 10: Breakdown Voltage Variation vs. Temperature

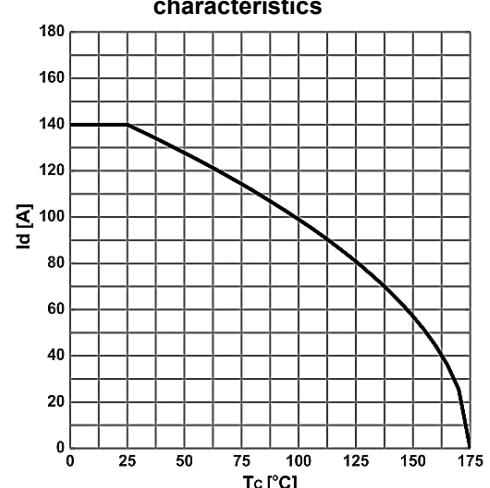
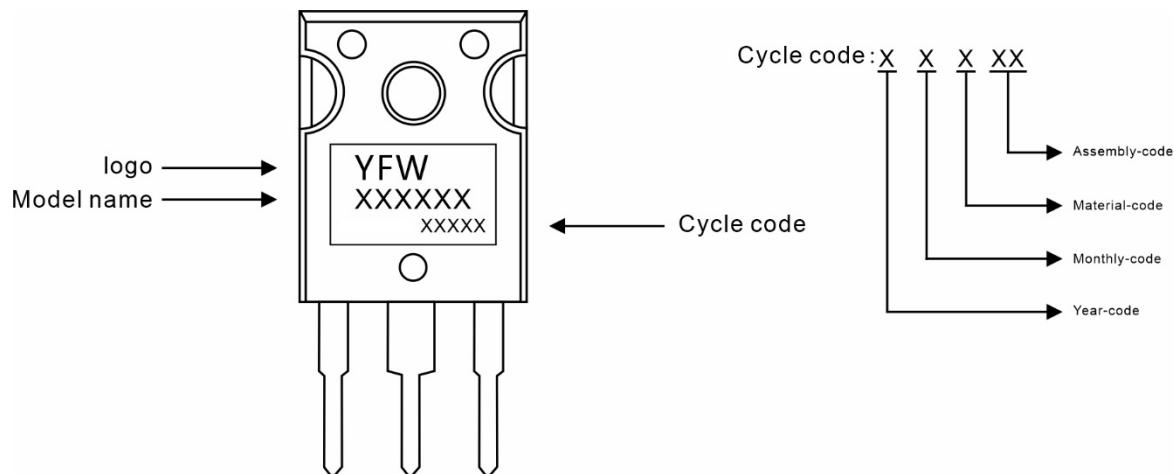


Figure 11: Maximum Drain Current

Marking Diagram



Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFWG200N15APS	TO-247S	0.158oz(4.48g)	30pcs/tube	600PCS/Box 2400PCS/Carton

Package Dimensions

TO-247S

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
E	15.40	15.80	0.60	0.62
D	19.50	20.50	0.77	0.80
S	5.30	5.50	0.21	0.22
ØR	4.50	5.50	0.18	0.22
ØP	3.40	3.80	0.13	0.15
L	14.0	14.5	0.55	0.57
L1	3.70	4.30	0.15	0.17
L2	18.5		0.73	
e	5.20	5.70	0.20	0.22
b	1.15	1.25	0.04	0.05
b1	1.80	2.20	0.07	0.09
b2	2.80	3.20	0.11	0.13
A	4.80	5.00	0.19	0.20
c	0.40	0.70	0.01	0.02
A1	2.30	2.45	0.09	0.10

The technical drawings show the front view of the component with dimensions E, D, S, ØR, ØP, L, L1, L2, e, b, b1, b2, A, and c. The back view shows the lead spacing and height A1. The heat-sink plane is also indicated.

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